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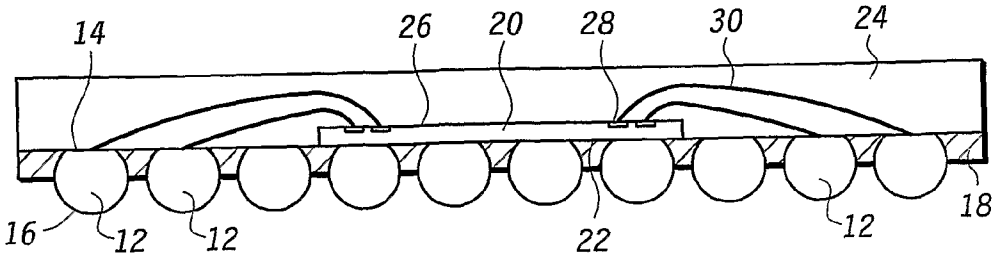
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(54) Title: PACKAGED DEVICE AND METHOD OF FORMING SAME



(57) Abstract: A method of packaging an integrated circuit die (12) includes the steps of loading an array of soft conductive balls (12) into recesses formed in a platen (50) and locating the platen (50) in a first part of a mold cavity. A second part of the mold is pressed against the balls (12) to flatten a surface of the balls. A first mold compound (18) then is injected into the mold cavity such that the mold compound (18) surrounds exposed portions of the balls (12). The balls are removed from the platen and a first side of an integrated circuit die (20) is attached to the balls (12). Die bonding pads (28) on a second side of the die are electrically connected to respective ones of the balls (12) surrounding the die (20), and then the die (20), the electrical connections (30), and a top portion of the conductive balls (12) is encapsulated with a second mold compound (24).

WO 2006/047028 A3